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REMARKS

Reconsideration of this application is respectfully requested in view of the foregoing amendment and the following remarks.

By the foregoing amendment, claims 1, 7, 22 and 23 have been amended, and claim 2 has been canceled. Accordingly, claims 1, 3-8, 11, 17-23 are now pending in this application.

In the Office Action, the Examiner objects to claims 1, 22 and 23 for minor informalities while also rejecting all of the pending claims over the prior art. To address the claim objections, Applicant has amended claims 1, 22 and 23, as suggested by the Examiner. However, there is no need to amend the claims to distinguish over the prior art, for the following reasons.

In rejecting the pending claims, the Examiner takes the position that US Patent No. 5,888,850 to Havens et al. teaches the steps of heating up the first and second solder materials beyond the melting points of the respective solder materials, solidifying the first and second solder materials, wherein the first solder material is caused to solidify earlier than the second solder material. However, column 8, lines 55-59 of this reference merely teaches that the conductors 5 (smaller solder balls) may have a higher melting point than the conductors 6 (larger solder balls). This feature is important for the invention of Havens et al. for reflowing (melting) only the conductors 6 used for connection to an external substrate while holding the conductors 5 in a stable state for keeping intact the required precise electrical coupling between the semiconductor chip 4 and the substrate 3, as clearly described at lines 59-64 of column 8 referred to by the Examiner himself. Thus, this reference clearly fails to teach the claimed steps of heating up the first and the second solder materials beyond the melting points of the respective solder materials, and solidifying the first and the second solder materials, wherein the first solder

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material is caused to solidify earlier than the second solder material in the solidifying step, contrary to the Examiner's holding.

In this way, the Examiner's interpretation of Havens et al. is entirely improper. Thus, the combination of Froloff et al. (fully discussed in the responses to the previous Office Actions) with Havens et al. does not yield the present invention defined in amended independent claims 1, 22 and 23.

In view of the foregoing all of the claims in this case are believed to be in condition for allowance. A prompt Notice of Allowance is earnestly solicited.

Should the Examiner have any questions or determine that any further action is desirable to place this application in even better condition for issue, the Examiner is encouraged to telephone applicants' undersigned representative at the number listed below.

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Respectfully submitted,

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